

FEATURES

- Member of the Texas Instruments Widebus™ Family
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Output Ports Have Equivalent 26-Ω Series Resistors, So No External Resistors Are Required
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

DESCRIPTION/ORDERING INFORMATION

This 16-bit transparent D-type latch is designed for 1.65-V to 3.6-V $\rm V_{CC}$ operation.

The SN74ALVCH162373 is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. This device can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components. \overline{OE} does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

多邦,专业PCB打样工厂,24小 16-BIT TRANSPARE	N74ALVCH162373
WITH 3	B-STATE OUTPUTS

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DGG OR DL PACKAGE (TOP VIEW)						
10E 1Q1 1Q2 GND 1Q3 1Q4 V _{CC} 1Q5 1Q6 GND 1Q7 1Q8 2Q1 2Q2 GND 2Q3 2Q4 V _{CC} 2Q5 2Q6	TOP VII 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16	48 47 46 45 44 43 42 43 42 38 37 36 37 36 37 36 37 36 37 36 37 36 37 36 37 36 37 36 37 38 37 38 37 38 37 38 37 38 37 38 37 38 37 38 37 38 37 38 37 38 37 38 37 38 37	AGE 1LE 1D1 1D2 GND 1D3 1D4 V _{CC} 1D5 1D6 GND 1D7 1D8 2D1 2D2 GND 2D3 2D4 V _{CC} 2D5 2D6 GND 2D7 2D8 2LE			

The outputs, which are designed to sink up to 12 mA, include equivalent $26-\Omega$ resistors to reduce overshoot and undershoot.

T _A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SSOP - DL	Tube	SN74ALVCH162373DL	ALVCH162373
40°C to 95°C	550P - DL	Tape and reel	SN74ALVCH162373LR	ALVUN102373
-40°C to 85°C	TSSOP - DGG	Tape and reel	SN74ALVCH162373GR	ALVCH162373
	VFBGA - GQL	Tape and reel	SN74ALVCH162373KR	VH2373

ORDERING INFORMATION

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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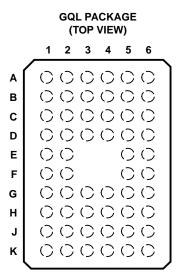
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas

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DESCRIPTION/ORDERING INFORMATION (CONTINUED)

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven data inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.



	1	2	3	4	5	6
Α	1 0E	NC	NC	NC	NC	1LE
в	1Q2	1Q1	GND	GND	1D1	1D2
С	1Q4	1Q3	V _{CC}	V _{CC}	1D3	1D4
D	1Q6	1Q5	GND	GND	1D5	1D6
Е	1Q8	1Q7			1D7	1D8
F	2Q1	2Q2			2D2	2D1
G	2Q3	2Q4	GND	GND	2D4	2D3
н	2Q5	2Q6	V _{CC}	V _{CC}	2D6	2D5
J	2Q7	2Q8	GND	GND	2D8	2D7
κ	2 <mark>0E</mark>	NC	NC	NC	NC	2LE

TERMINAL ASSIGNMENTS(1)

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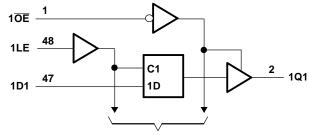
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(1) NC - No internal connection

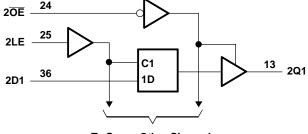
FUNCTION TABLE (each 8-bit section)

	INPUTS	OUTPUT	
OE	LE	D	Q
L	Н	Н	Н
L	н	L	L
L	L	Х	Q ₀
н	Х	х	Z

LOGIC DIAGRAM (POSITIVE LOGIC)



To Seven Other Channels



To Seven Other Channels

Pin numbers shown are for the DGG and DL packages.



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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	4.6	V
VI	Input voltage range ⁽²⁾		-0.5	4.6	V
Vo	Output voltage range ⁽²⁾⁽³⁾		-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V ₁ < 0		-50	mA
I _{OK}	Output clamp current	V ₀ < 0		-50	mA
I _O	Continuous output current			±50	mA
	Continuous current through each V _{CC} or GN	ND		±100	mA
		DGG package		70	
θ_{JA}	Package thermal impedance ⁽⁴⁾	DL package		63	°C/W
		GQL package		42	
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) This value is limited to 4.6 V maximum.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage		1.65	3.6	V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65 imes V_{CC}$	V _{CC}	
V _{IH}	High-level input voltage	V_{CC} = 2.3 V to 2.7 V	1.7	V _{CC}	V
		$V_{CC} = 2.7 V \text{ to } 3.6 V$	2	V _{CC}	
		V_{CC} = 1.65 V to 1.95 V	0	$0.35 \times V_{CC}$	
V _{IL}	Low-level input voltage	V_{CC} = 2.3 V to 2.7 V	0	0.7	V
		$V_{CC} = 2.7 V \text{ to } 3.6 V$	0	0.8	
Vo	Output voltage		0	V _{CC}	V
	High-level output current	V _{CC} = 1.65 V		-2	
		$V_{CC} = 2.3 V$		-6	mA
I _{OH}		$V_{CC} = 2.7 V$		-8	IIIA
		$V_{CC} = 3 V$		-12	
		V _{CC} = 1.65 V		2	
		V _{CC} = 2.3 V		6	
I _{OL}	Low-level output current	V _{CC} = 2.7 V			
		$V_{CC} = 3 V$		12	
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V
T _A	Operating free-air temperature		-40	85	°C

 All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{cc}	MIN	TYP ⁽¹⁾ MAX	UNIT		
	I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} - 0.2				
	I _{OH} = -2 mA	1.65 V	1.2				
	I _{OH} = -4 mA	2.3 V	1.9				
V _{OH}		2.3 V	1.7		V		
	I _{OH} = -6 mA	3 V	2.4				
	I _{OH} = -8 mA	2.7 V	2				
	I _{OH} = -12 mA	3 V	2				
	I _{OL} = 100 μA	1.65 V to 3.6 V		0.2			
	I _{OL} = 2 mA	1.65 V		0.45			
	I _{OL} = 4 mA	2.3 V		0.4			
V _{OL}		2.3 V		0.55	V		
	$I_{OL} = 6 \text{ mA}$	3 V		0.55			
	I _{OL} = 8 mA	2.7 V		0.6			
	I _{OL} = 12 mA	3 V		0.8]		
I _I	$V_{I} = V_{CC}$ or GND	3.6 V		±5	μA		
	V _I = 0.58 V	1.65 V	25				
	V _I = 1.07 V	1.65 V	-25				
	V _I = 0.7 V	2.3 V	45				
I _{I(hold)}	V _I = 1.7 V	2.3 V	-45		μA		
. ,	V _I = 0.8 V	3 V	75				
	V _I = 2 V	3 V	-75				
	V _I = 0 to 3.6 V ⁽²⁾	3.6 V		±500			
I _{oz}	$V_{O} = V_{CC}$ or GND	3.6 V		±10	μA		
I _{cc}	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	3.6 V		40	μA		
Δl _{CC}	One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V		750	μA		
Control inputs	V V 015	0.01/	3		_		
C _i Data inputs	$V_{I} = V_{CC} \text{ or } GND$	3.3 V		6	pF		
C _o Outputs	$V_0 = V_{CC}$ or GND	3.3 V		7	pF		

TEXAS

INSTRUMENTS www.ti.com

(1) (2)

All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$. This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V _{CC} = 1.8 V ± 0.15 V			$ \begin{array}{c c} = 1.8 \ V \\ 0.15 \ V \\ \pm \ 0.2 \ V \\ \end{array} \begin{array}{c} V_{CC} = 2.5 \ V \\ \pm \ 0.2 \ V \\ \end{array} \begin{array}{c} V_{CC} = 2.7 \ V \\ \end{array} \begin{array}{c} V_{CC} \end{array} $		V _{CC} = 3.3 V ± 0.3 V	UNIT
		MIN MAX	MIN MA	X MIN MAX	MIN MAX			
tw	Pulse duration, LE high or low	3.3	3.3	3.3	3.3	ns		
t _{su}	Setup time, data before LE \downarrow	1.1	1.1	1.1	1.1	ns		
t _h	Hold time, data after LE \downarrow	1.1	1.1	1.1	1.1	ns		



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SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO	V _{CC} = ± 0.7	1.8 V 5 V	V _{CC} = 2 ± 0.2	2.5 V 2 V	V _{CC} =	2.7 V	V _{CC} = ± 0.	3.3 V 3 V	UNIT
	(INFOT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	D	0	1	6.3	1	5.3	1	4.5	1.1	4	
^L pd	LE	Q	1	6.6	1	5.6	1	5	1	4.2	ns
t _{en}	ŌĒ	Q	1	7.2	1	6.5	1.5	6	1	5	ns
t _{dis}	OE	Q	1	6.5	1	5.6	1.5	5.5	1.4	4.5	ns
t _{sk(o)}				1		0.5		0.5		0.5	ns

OPERATING CHARACTERISTICS

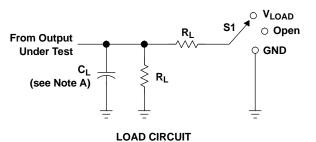
 $T_A = 25^{\circ}C$

	PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT
<u> </u>	Dower dissipation consultance	Outputs enabled	C = 50 pE f = 10 MHz	20	22	26	'n
Cpd	Power dissipation capacitance	Outputs disabled	$C_{L} = 50 \text{ pF}, f = 10 \text{ MHz}$	6	6.5	8	рF

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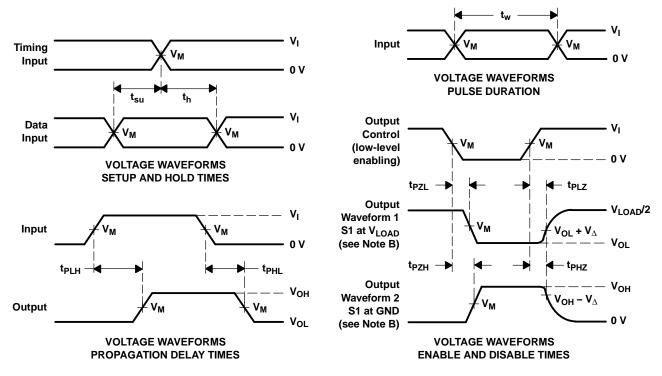


PARAMETER MEASUREMENT INFORMATION



TEST	S1
t _{pd}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

v _{cc}	INPUT		V	V	<u>^</u>	Б	V
	VI	t _r /t _f	V _M	V _{LOAD}	CL	RL	V_{Δ}
1.8 V	V _{CC}	≤2 ns	V _{CC} /2	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



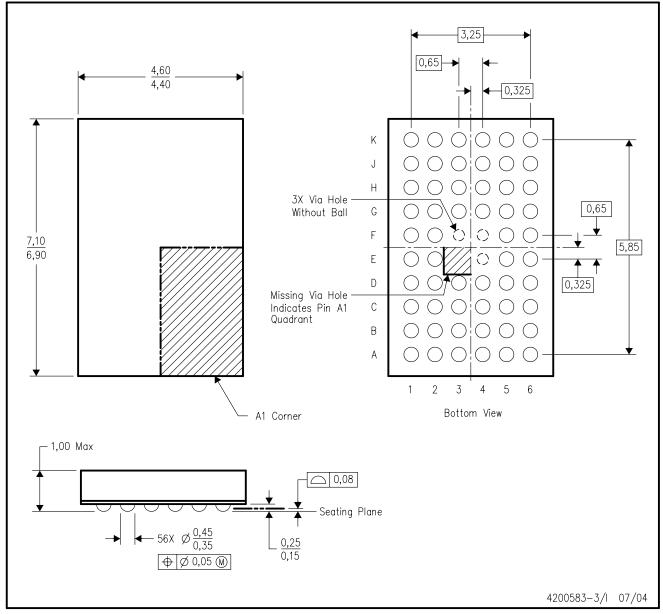
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω .
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES:

A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BA.
- D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.

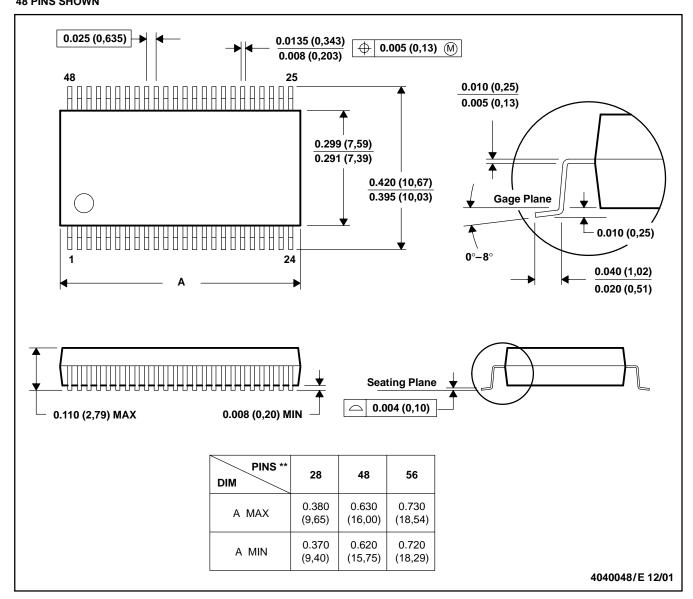


MECHANICAL DATA

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

PLASTIC SMALL-OUTLINE PACKAGE

DL (R-PDSO-G**) 48 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

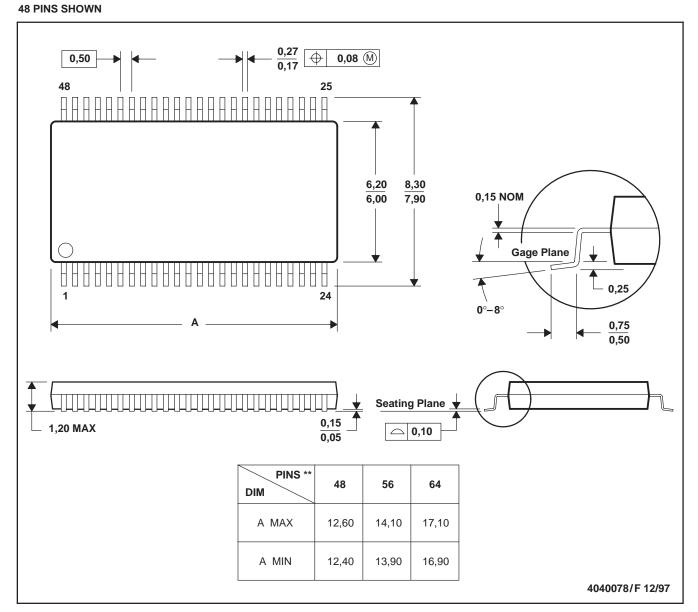


MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

PLASTIC SMALL-OUTLINE PACKAGE

DGG (R-PDSO-G**)



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153



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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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